EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	679	((stretch$4 expan$7) near5 (tape ribbon support$4)) same ((separat$4 cut$4 dicing) with (wafer dice die semiconduct$4 silicon))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:00
L2	29	1 same (pick$4 with plac$5 with (individual$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:31
L3	16	2 and (laser with (cut$4 seperat$4 dic$4 machin$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:31
L4	0	2 and laser not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:30
L5	124	1 same ((pick$4 plac$5 transfer$4) near9 (individual$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:01
L6	33	5 and (laser with (cut$4 seperat$4 dic$4 machin$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:31
L7	17	6 not 3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:47
L8	47	1 and (push$3 adj (up upward$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:45
L9	39	1 and (push$3 adj (up upward$4)) with (stretch$4 expan$7 tape ribbon support$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:51

L10	43	1 and (push$3 adj (up upward$4)) with (stretch$4 expan$7 tape ribbon support$4 needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:53
L11	43	1 and ((push$3 adj (up upward$4)) pushup) with (stretch$4 expan$7 tape ribbon support$4 needle)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 10:52
L12	27	1 and (push$3 adj (up upward$4)) with (stretch$4 expan$7 tape ribbon support$4 needle) and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:11
L13	17580	b23k026$.ipc.	JPO	OR	ON	2006/03/01 10:59
L14	362997	h01l021$.ipc.	JPO	OR	ON	2006/03/01 11:00
L15	379608	13 14	JPO	OR	ON	2006/03/01 11:00
L16	66	15 and (((stretch$4 expan$7) near5 (tape ribbon support$4)) same ((separat$4 cut$4 dicing) with (wafer dice die semiconduct$4 silicon)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:00
L17	165	15 and (((stretch$4 expan$7) and (tape ribbon support$4)) and ((separat$4 cut$4 dicing) and (wafer dice die semiconduct$4 silicon)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:01
L18	31	17 and ((pick$4 plac$5 transfer$4) and (individual$4 dice die semiconductor))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:05
L19	3	18 and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:02
L20	1	18 and ((push$3 adj (up upward$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:12
L21	1	17 and ((push$3 adj (up upward$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:12

L22	1070	15 and ((push$3 adj (up upward$4)) pushup)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:13
L23	93	15 and ((push$3 adj (up upward$4)) pushup) and needle	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:13
L24	60	23 and (individual$4 dice die semiconductor)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:14
L25	2	24 and (stretch$4 expand$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:14
L26	4	(frame with ((push$5 adj up$5) pushup) with (expand$4 stretch$4)) and ((die dice dicing semiconductor) with (scrib$4 cut$4 seperat$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 11:52
L27	2	"20050221589"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 12:31